

FILM ADHESIVE FOR SEALING, FILM LAMINATE FOR SEALING AND  
SEALING METHOD

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ABSTRACT

10 A film adhesive for sealing a plurality of chip-type devices on  
a substrate at one time, including an adhesive layer of an  
adhesive composition which exhibits a minimum value of a  
storage modulus of elasticity before curing from  $1 \times 10^3$  to  $5 \times$   
15  $10^5$  Pa measured by using a dynamic visco-elasticity measuring  
apparatus while elevating the temperature from  $80^\circ\text{C}$  to  $150^\circ\text{C}$  at  
an elevating temperature rate of  $2.4^\circ\text{C}/\text{min}$  and at a shearing  
rate of  $6.28 \text{ rad/sec}$  and a storage modulus of elasticity after  
curing from  $5 \times 10^5$  to  $5 \times 10^7$  Pa measured by using a dynamic  
visco-elasticity measuring apparatus at a sample temperature of  
 $150^\circ\text{C}$  in a tensile mode at a measuring frequency of  $6.28$   
rad/sec.